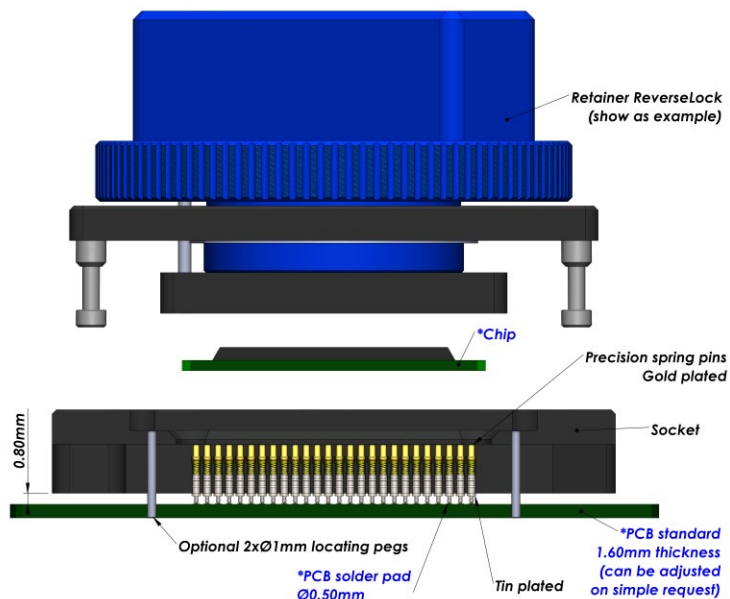
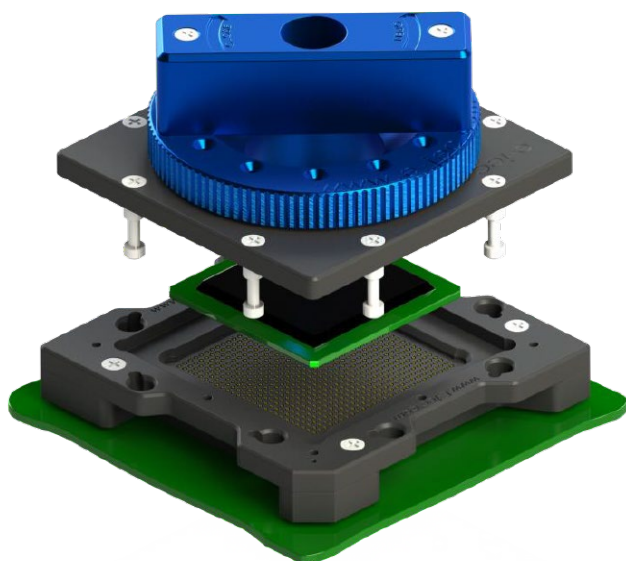
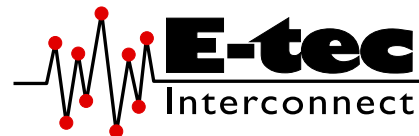


# Standard SMT soldering Test Socket

For LGA / QFN / MLF / MLP / LCC Package

1.00 mm pitch (from 1.00 mm up to 1.26 mm)



**E-tec Interconnect AG is the world leading Test socket manufacturer**

The SMT socket uses the same footprint as your chip. Socket is simply placed and reflowed onto the PCB in the same way as the chip and it only requires a small amount of additional board space. SMT type sockets are available with all retention systems. We aim to solve your requirements. Please note, we will always request the chip data to ensure we offer a compatible socket. For SMT sockets in general, E-tec Interconnect AG recommends the use of locating pegs, which can be soldered to the PCB for added mechanical strength.

| Specifications contact type code 1030 |                                 |                   |                 |
|---------------------------------------|---------------------------------|-------------------|-----------------|
| Application                           | Surface mouting                 | Force             | 25 gr           |
| Mounting                              | SMT                             | Current rating    | 1.8 A           |
| Bandwidth (GHz@-1dB)                  | 2.8(6.6) GHz                    | Capacitance pF    | 0.62 pF         |
| Contact resistance                    | <100mOhm                        | Inductance nH     | 1.97 nH         |
| Chip contact tip shape                | Single Point tip or Concave tip | Temperature range | -55°C to +150°C |
| PCB tip shape                         | SMT                             | Mating cycles     | 100 K           |

## How to order

**LP # #### -1030 - ##### 95 #**

|  |   |  |  |  |
|--|---|--|--|--|
| <p><b>Shape of tip</b></p> <p>P : Pointed</p> <p><b>Options:</b></p> <p>C : Crown</p>  | <p><b>Nbr of contacts</b></p> <p>Depends on ballcount of chip</p> | <p><b>Contact type</b></p> <p>30 : Standard SMT – Dimension A = 0.80 mm</p>  | <p><b>Plating</b></p> <p>95 : Tin / Gold</p> <p>Other on request</p> | <p><b>Option code</b> (see page 16-19)</p> <p>D : Dead bug</p> <p>M : Multi frames</p> <p>U : Multi packages</p> <p>C : Converter plate</p> <p>S : Custom opening slot</p> <p>L : Locating pegs</p> <p>H : Heatsink</p> <p>F : Fan + Heatsink</p> <p>P : Thermal drain pad</p> <p>W : Transparent lid</p> <p>I : Steel retention lid</p> <p>B : Aluminium retention lid</p> <p>G : Handling button</p> |
| <p><b>Retention frame type (Lid)</b> (see page 12-15)</p> <p>W : TwistLock</p> <p>F : FastLock</p> <p>B : SpringLock</p> <p>H : Open Clamshell Alu (&lt;200 contacts)</p> <p>J : Clamshell Alu (&gt;200 contacts)</p> <p>L : Open Lever Clamshell Alu (&gt;200 contacts)</p> |   | <p><b>Grid code / Config. code</b></p> <p>Will be given by the factory after receipt of the chip datasheet</p>   |  |  |
|  |   | <p>S : ScrewLock</p> <p>Q : Open QuickLock (&lt;200 contacts)</p> <p>D : QuickLock (&gt;200 contacts)</p> <p>M : Injection Molded ClamShell</p> <p>R : ReverseLock</p> <p>T : SlimLock</p> |  |  |

